

MM74HC132

Quad 2-Input NAND Schmitt Trigger

General Description

The MM74HC132 utilizes advanced silicon-gate CMOS technology to achieve the low power dissipation and high noise immunity of standard CMOS, as well as the capability to drive 10 LS-TTL loads.

The 74HC logic family is functionally and pinout compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

- Typical propagation delay: 12 ns
- Wide power supply range: 2V–6V
- Low quiescent current: 20 μ A maximum (74HC Series)
- Low input current: 1 μ A maximum
- Fanout of 10 LS-TTL loads
- Typical hysteresis voltage: 0.9V at $V_{CC}=4.5V$

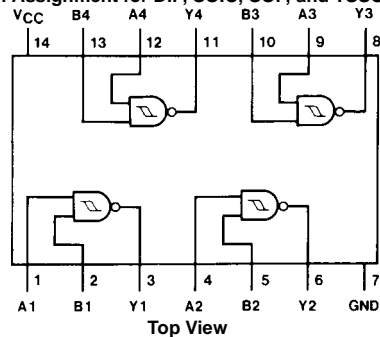
Ordering Code:

Order Number	Package Number	Package Description
MM74HC132M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150" Narrow Body
MM74HC132SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC132MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC132N	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

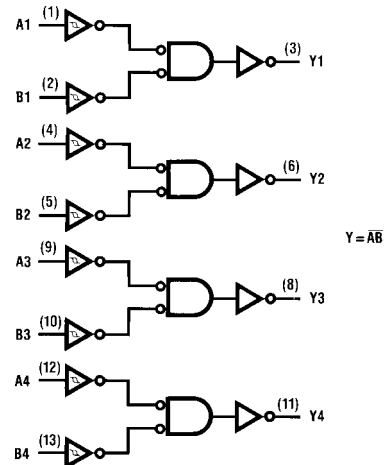
Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code. (Tape and Reel not available in N14A.)

Connection Diagram

Pin Assignment for DIP, SOIC, SOP, and TSSOP



Logic Diagram



Absolute Maximum Ratings (Note 1)

(Note 2)

Supply Voltage (V_{CC})	-0.5 to +7.0V
DC Input Voltage (V_{IN})	-1.5 to $V_{CC} + 1.5V$
DC Output Voltage (V_{OUT})	-0.5 to $V_{CC} + 0.5V$
Clamp Diode Current (I_{IK}, I_{OK})	± 20 mA
DC Output Current, per pin (I_{OUT})	± 25 mA
DC V_{CC} or GND Current, per pin (I_{CC})	± 50 mA
Storage Temperature Range (T_{STG})	-65°C to +150°C
Power Dissipation (P_D)	
(Note 3)	600 mW
S.O. Package only	500 mW

Lead Temperature (T_L)

(Soldering 10 seconds)

260°C

Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V_{CC})	2	6	V
DC Input or Output Voltage (V_{IN}, V_{OUT})	0	V_{CC}	V
Operating Temperature Range (T_A)	-40	+125	°C

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.**Note 2:** Unless otherwise specified all voltages are referenced to ground.**Note 3:** Power Dissipation temperature derating — plastic "N" package: —**DC Electrical Characteristics** (Note 4)

Symbol	Parameter	Conditions		V _{CC}	T _A = 25°C		T _A = -40 to 85°C	T _A = -40 to 125°C	Units
					Typ	Guaranteed Limits			
V _{T+}	Positive Going Threshold Voltage		Min	2.0V		1.0	1.0	1.0	V
				4.5V		2.0	2.0	2.0	V
				6.0V		3.0	3.0	3.0	V
			Max	2.0V		1.5	1.5	1.5	V
				4.5V		3.15	3.15	3.15	V
				6.0V		4.2	4.2	4.2	V
V _{T-}	Negative Going Threshold Voltage		Min	2.0V		0.3	0.3	0.3	V
				4.5V		0.9	0.9	0.9	V
				6.0V		1.2	1.2	1.2	V
			Max	2.0V		1.0	1.0	1.0	V
				4.5V		2.2	2.2	2.2	V
				6.0V		3.0	3.0	3.0	V
V _H	Hysteresis Voltage		Min	2.0V		0.2	0.2	0.2	V
				4.5V		0.4	0.4	0.4	V
				6.0V		0.5	0.5	0.5	V
			Max	2.0V		1.0	1.0	1.0	V
				4.5V		1.4	1.4	1.4	V
				6.0V		1.5	1.5	1.5	V
V _{OH}	Minimum HIGH Level Output Voltage	V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 20 μA V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 4.0 mA I _{OUT} ≤ 5.2 mA	2.0V	2.0	1.9	1.9	1.9	V	
			4.5V	4.5	4.4	4.4	4.4	V	
			6.0V	6.0	5.9	5.9	5.9	V	
			4.5V	4.2	3.98	3.84	3.7	V	
			6.0V	5.7	5.48	5.34	5.2	V	
			6.0V	5.7	5.48	5.34	5.2	V	
V _{OL}	Maximum LOW Level Output Voltage	V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 20 μA V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 4.0 mA I _{OUT} ≤ 5.2 mA	2.0V	0	0.1	0.1	0.1	V	
			4.5V	0	0.1	0.1	0.1	V	
			6.0V	0	0.1	0.1	0.1	V	
			4.5V	0.2	0.26	0.33	0.4	V	
			6.0V	0.2	0.26	0.33	0.4	V	
			6.0V	0.2	0.26	0.33	0.4	V	
I _{IN}	Maximum Input Current	V _{IN} = V _{CC} or GND	6.0V		±0.1	±1.0	±1.0	μA	
I _{CC}	Maximum Quiescent Supply Current	V _{IN} = V _{CC} or GND I _{OUT} = 0 μA	6.0V		2.0	20	40	μA	

Note 4: For a power supply of $5V \pm 10\%$ the worst case output voltages (V_{OH} and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at $V_{CC} = 5.5V$ and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

AC Electrical Characteristics
 $V_{CC} = 5V$, $T_A = 25^\circ C$, $C_L = 15\text{ pF}$, $t_r = t_f = 6\text{ ns}$

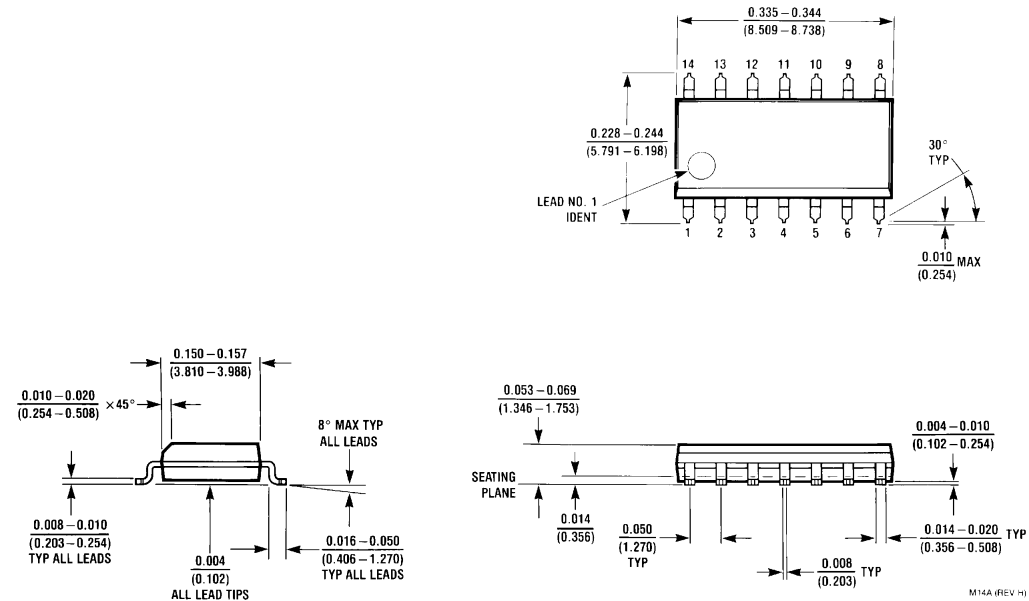
Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
t_{PHL} , t_{PLH}	Maximum Propagation Delay		12	20	ns

AC Electrical Characteristics
 $V_{CC} = 2.0V$ to $6.0V$, $C_L = 50\text{ pF}$, $t_r = t_f = 6\text{ ns}$ (unless otherwise specified)

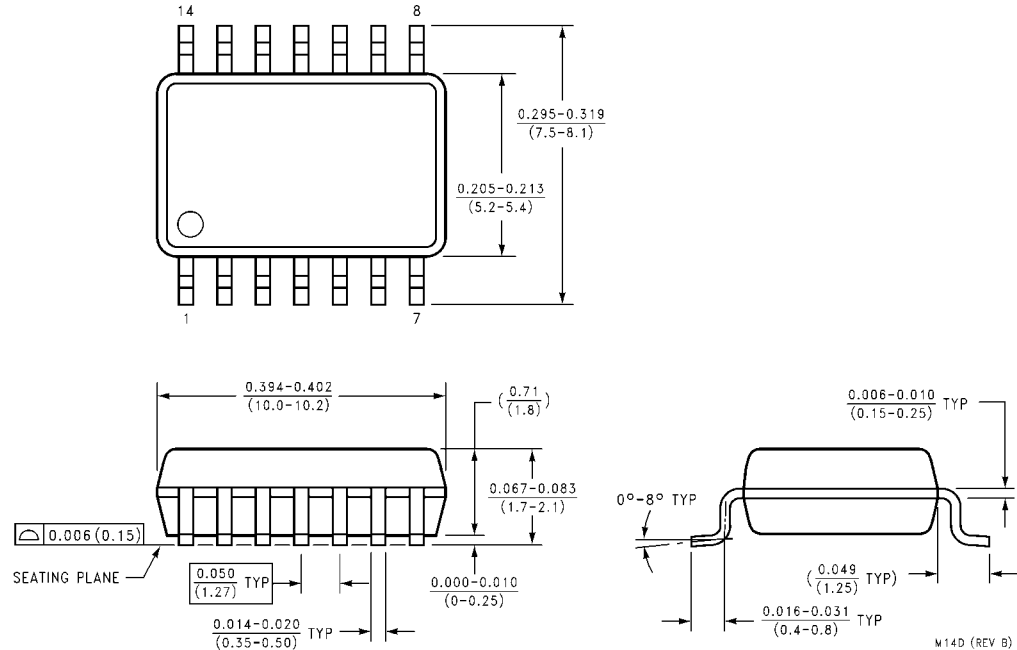
Symbol	Parameter	Conditions	V _{CC}	T _A = 25°C		T _A = −40 to 85°C	T _A = −55 to 125°C	Units
				Typ	Guaranteed Limits			
t _{PHL} , t _{PLH}	Maximum Propagation Delay		2.0V	63	125	158	186	ns
			4.5V	13	25	32	37	ns
			6.0V	11	21	27	32	ns
t _{TLH} , t _{THL}	Maximum Output Rise and Fall Time		2.0V	30	75	95	110	ns
			4.5V	8	15	19	22	ns
			6.0V	7	13	16	19	ns
C _{PD}	Power Dissipation Capacitance (Note 5)	(per gate)		130				pF
C _{IN}	Maximum Input Capacitance				5	10	10	pF

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

Physical Dimensions inches (millimeters) unless otherwise noted



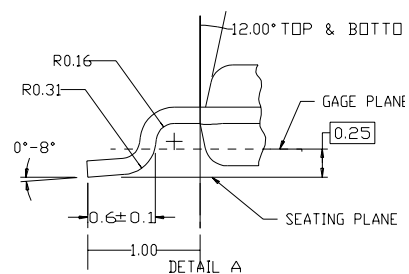
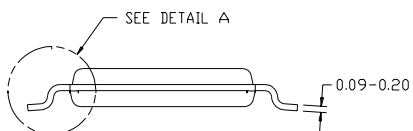
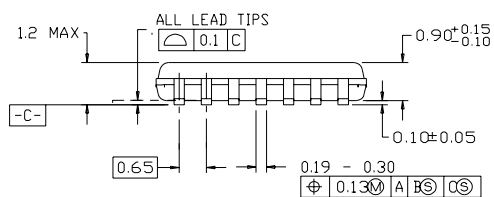
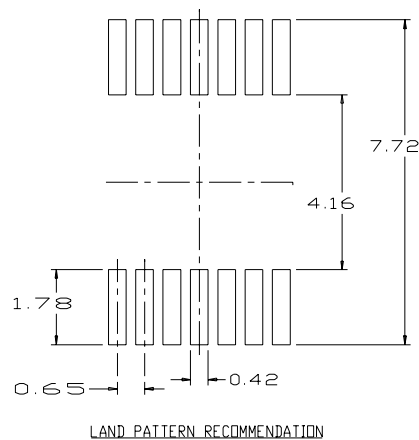
**14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150" Narrow Body
Package Number M14A**



**14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M14D**

PIN #1 IDENT.

ALL LEAD TIPS



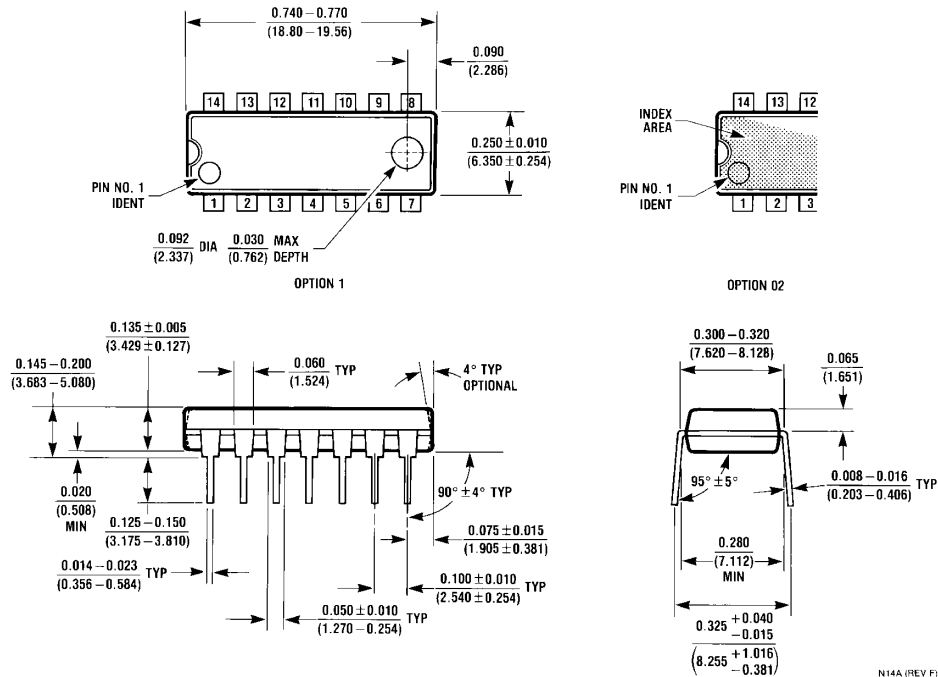
A. CONFORMS TO JEDEC REGISTRATION MO-153 VARIATION AB,
REF NOTE 6, DATED 7/93

B. DIMENSIONS ARE IN MILLIMETERS

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH,
AND TIE BAR EXTRUSIONS

**14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC14**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



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